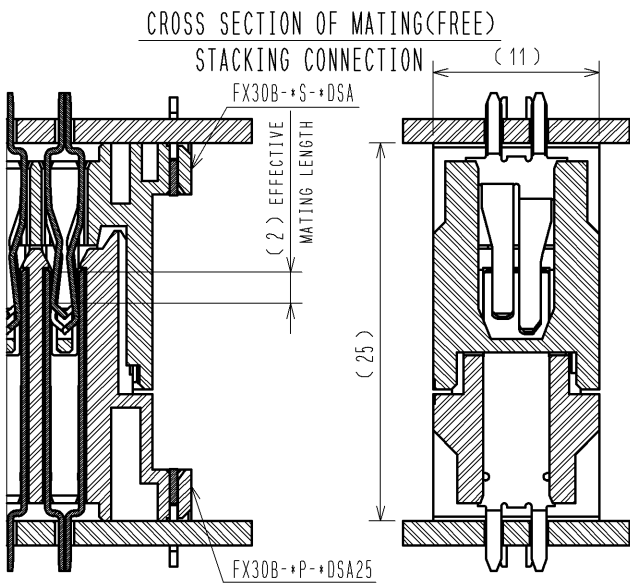
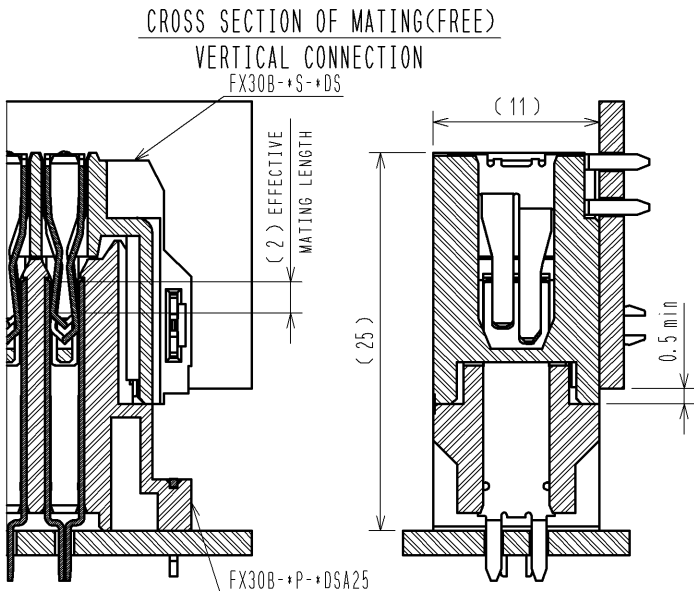
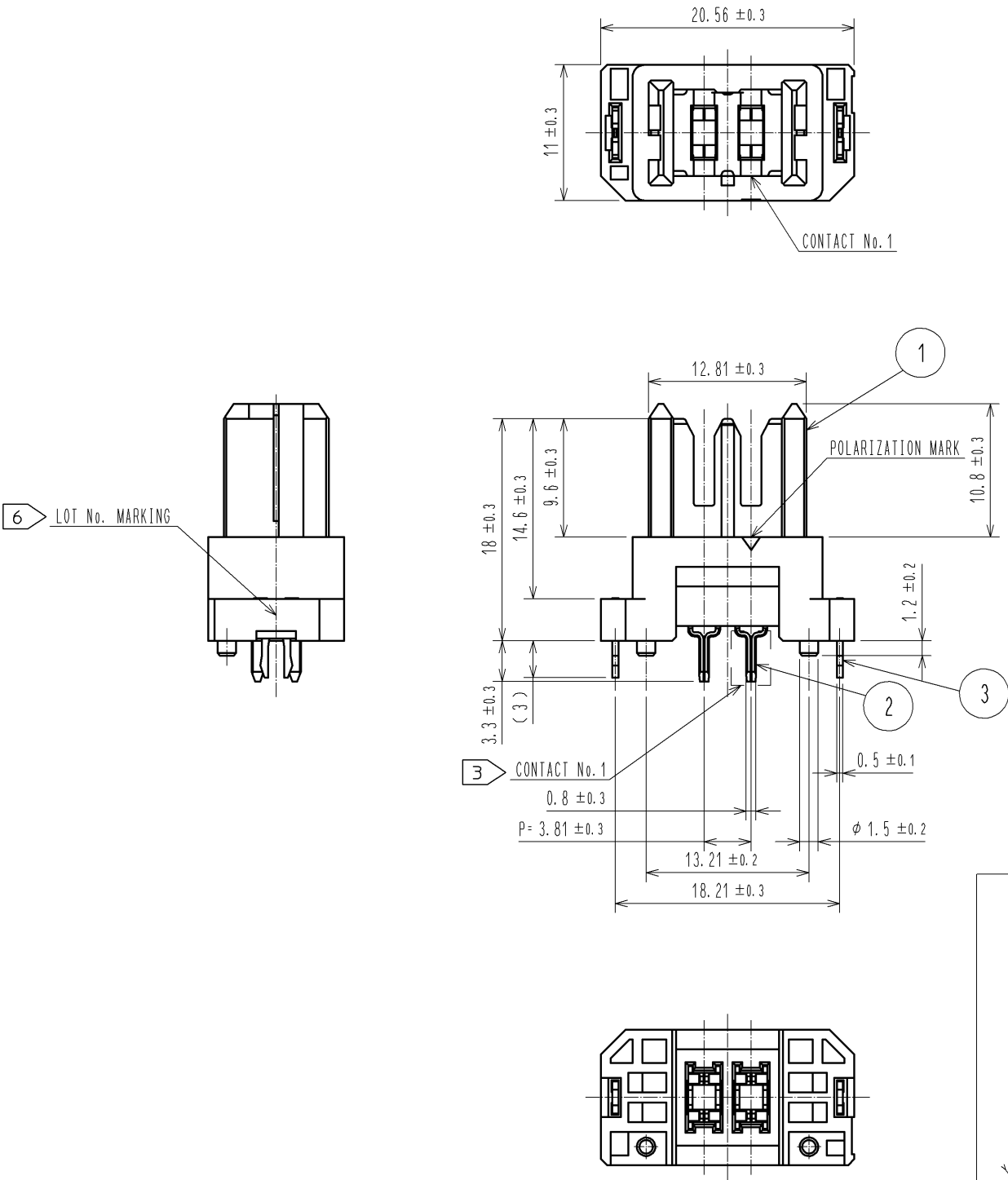
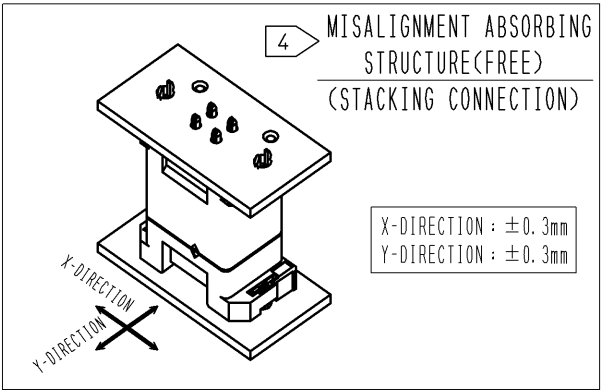
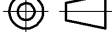




- NOTE
- 1 THIS PRODUCT IS PACKAGED IN TRAY. (49pcs/TRAY)
 - 2 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHITCH DOSEN' T AFFECT QUALITY LEVEL. ALSO, BLACK SPOT COULD BE OBSERVED ON THE SURFACE OF HOUSING.
 - 3 FOR THE CONTACT NO., ADJACENT TWO PAIRS OF LEADS PLACED BACK-TO-BACK (4 LEADS IN TOTAL) COMPOSE ONE LINE.
 - 4 MISALIGNMENT ABSORBING RANGE: ±0.3mm max.
 - 5 THE DIMENSION IN PARENTHESES ARE FOR REFERENCES.
 - 6 LOT NO. IS INDICATED AT EITHER ONE OF THE POSITION AS SHOWN.



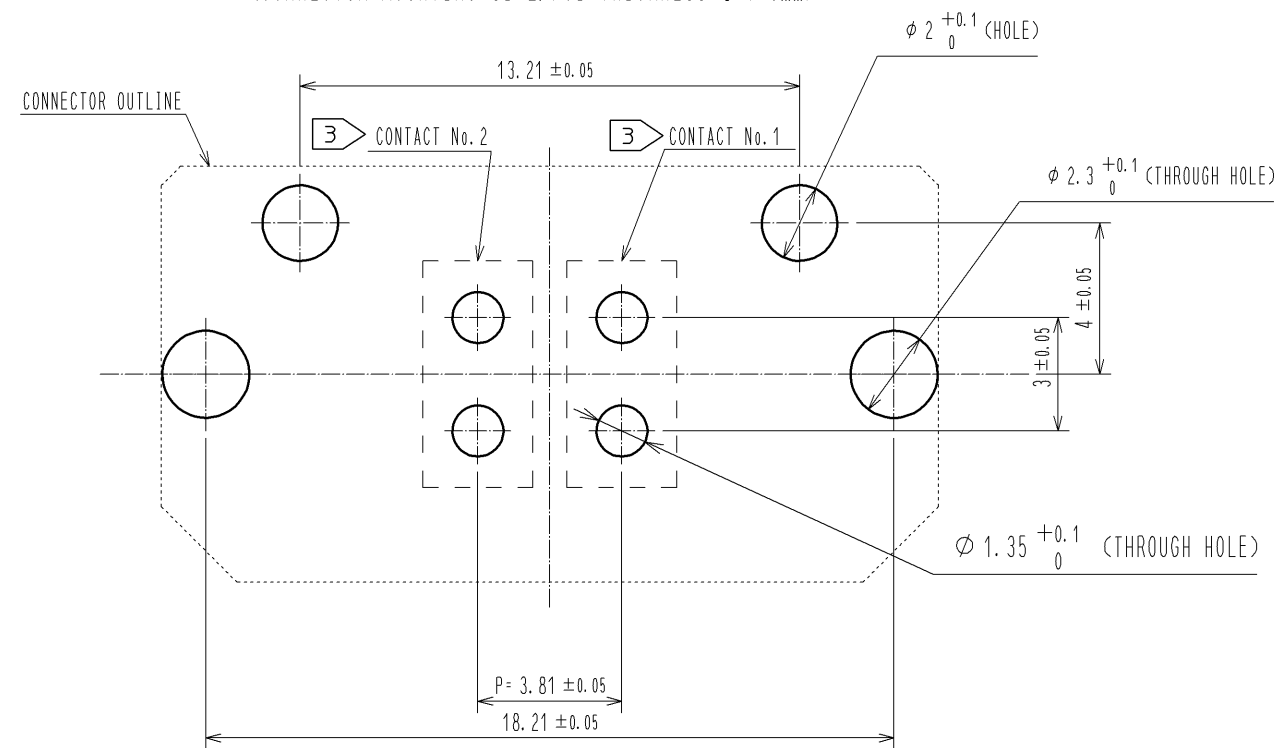
2	COPPER ALLOY	CONTACT AREA:GOLD-PLATING 0.1 μm			4	POLYSTYRENE				
		LEAD AREA:TIN-PLATING 1.0 μm								
		UNDER PLATING:NICKEL 1.0 μm								
1	POLYAMIDE	BLACK UL94V-0			3	PHOSPHOR BRONZE	TIN-PLATING 3.0 μm			
							UNDER PLATING:NICKEL 1.0 μm			
NO.	MATERIAL	FINISH , REMARKS			NO.	MATERIAL	FINISH , REMARKS			
UNITS mm				SCALE 2 : 1	COUNT 	DESCRIPTION OF REVISIONS		DESIGNED	CHECKED	DATE
 HIROSE ELECTRIC CO., LTD.		APPROVED :HS. OKAWA			13. 03. 07	DRAWING NO. EDC3-347259-00				
		CHECED :KI. HIROKAWA			13. 03. 07	PART NO. FX30B-2P-3. 81DSA25				
		DESIGNED :DK. AIMOTO			13. 03. 07	CODE NO. CL570-3200-8-00				
		DRAWN :DK. AIMOTO			13. 03. 07					
 1/2										

HRS

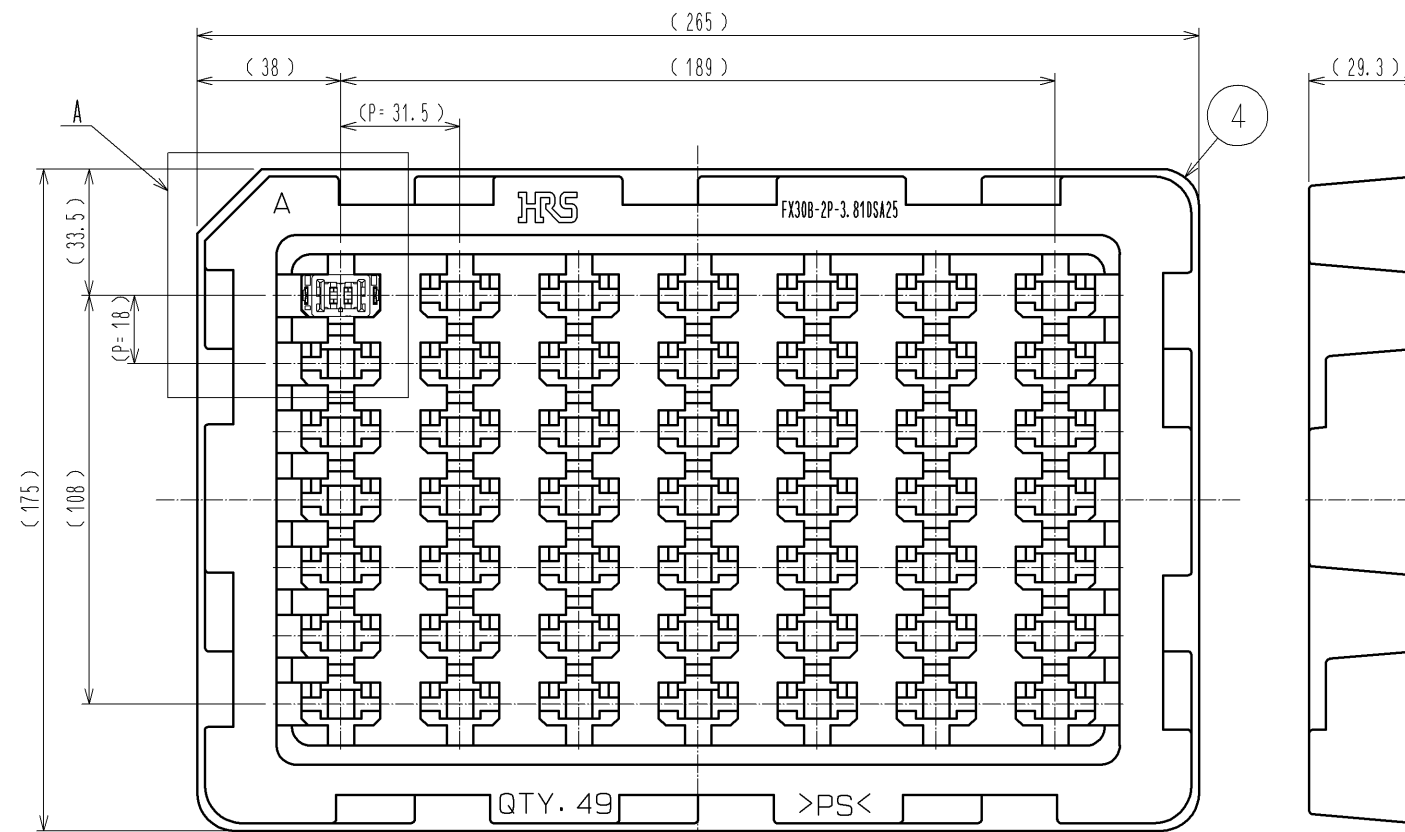
HIROSE
ELECTRIC
CO., LTD.

APPROVED : HS. OKAWA 13. 03. 07
CHECED : KI. HIROKAWA 13. 03. 07
DESIGNED : DK. AIMOTO 13. 03. 07
DRAWN : DK. AIMOTO 13. 03. 07

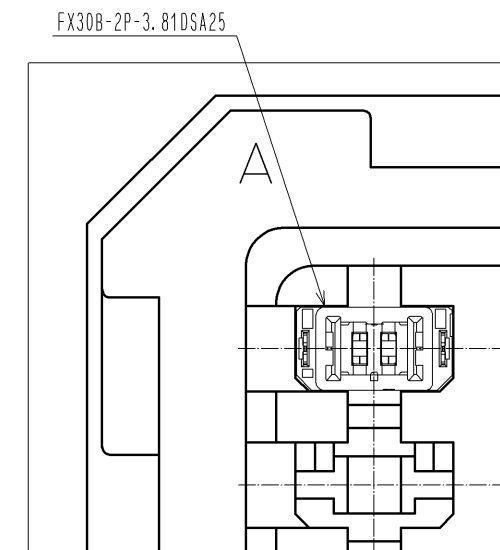
13. 03. 07
13. 03. 07
13. 03. 07
13. 03. 07

RECOMMENDED HOLE PATTERN DIMENSION OF PCB(5:1)
(CONNECTOR MOUNTING SIDE, PCB THICKNESS: t=1.6mm)

1 DRAWING FOR PACKAGING(1:2)



A(1:1)

**HRS**

DRAWING NO.	EDC3-347259-00
PART NO.	FX30B-2P-3.81DSA25
CODE NO.	CL570-3200-8-00

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